	Reference Specification
Lea	aded MLCC for Consumer Electronics & Industrial Equipment RDE Series
Product specific:	ations in this catalog are as of Apr. 2025, and are subject to change or
obsolescence wi	

Please refer to the product information page for more information on ceramic capacitors.→ Ceramic capacitor product information Various data can be obtained directly from the product search. \rightarrow <u>Product search (SMD)</u> / <u>Product search (Lead Type)</u>

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1. Scope

This product specification is applied to Leaded MLCC RDE series.

1.Specific applications:

• Consumer Equipment: Products that can be used in consumer equipment such as home appliances, audio/visual equipment, communication equipment, information equipment, office equipment, and household robotics, and whose functions are not directly related to the protection of human life and property.

•Industrial Equipment: Products that can be used in industrial equipment such as base stations, manufacturing equipment, industrial robotics equipment, and measurement equipment, and whose functions do not directly relate to the protection of human life and property.

•Medial Equipment [GHTF A/B/C] except for Implant Equipment: Products suitable for use in medical devices designated under the GHTF international classifications as Class A or Class B (the functions of which are not directly involved in protection of human life or property) or in medical devices other than implants designated under the GHTF international classifications as Class C (the malfunctioning of which is considered to pose a comparatively high risk to the human body).

•Automotive infotainment/comfort equipment: Products that can be used for automotive equipment such as car navigation systems and car audio systems that do not directly relate to human life and whose structure, equipment, and performance are not specifically required by law to meet technical standards for safety assurance or environmental protection.

2.Unsuitable Application: Applications listed in "Limitation of applications" in this product specification. WE DISCLAIM ANY LOSS AND DAMAGES ARISING FROM OR IN CONNECTION WITH THE PRODUCTS INCLUDING BUT NOT LIMITED TO THE CASE SUCH LOSS AND DAMAGES CAUSED BY THE UNEXPECTED ACCIDENT,

IN EVENT THAT THE PRODUCT IS APPLIED FOR THE PURPOSE WHICH IS SPECIFIED ABOVE AS THE UNSUITABLE APPLICATION FOR THE PRODUCT.

2. Rating

Part Number Configuration

ex.)

RDE	C7	1E	476	М	W	K1	H03	В
Series	Temperature	Rated	Capacitance	Capacitance	Dimension	Lead	Individual	Package
	Characteristics	Voltage		Tolerance	(LxW)	Style	Specification	

• Temperature Characteristics

Code	Temp. Char.	Temp. Range	Cap. Change	Standard Temp.	Operating Temp. Range
C7	X7S (EIA code)	-55~125°C	+/-22%	25°C	-55~125°C
R7	X7R (EIA code)	-55∼125°C	+/-15%	25°C	-55~125°C

Rated Voltage

Code	Rated voltage
1E	DC25V
1H	DC50V
2A	DC100V

	Conceitores Telerance	_
Code K	Capacitance Tolerance +/-10%	
М	+/-20%	
Dimension (LxW) Please refer to [Part Lead Style	number list].	
*Lead wire is "solder		
Code	Lead Style	Lead spacing (mm)
K1 M1	Inside crimp type Inside crimp taping type	5.0+/-0.8
P1	Outside crimp type	2.5+/-0.8
S1	Outside crimp taping type	2.5+0.4/-0.2
A B	Taping type of Ammo Bulk type	

Reference only

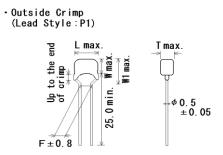
3. Marking

Temp. char.	:	Letter code : C (X7R/X7S Char. Except dimension code : 0,1)
Capacitance	:	3 digit numbers
Capacitance tolerance	:	Code
Rated voltage	:	Letter code : 2 (DC25V. Except dimension code : 0,1)
		Letter code : 5 (DC50V. Except dimension code : 0,1)
		Letter code : 1 (DC100V. Except dimension code : 0,1)
Company name code	:	Abbreviation : 🚱 (Except dimension code : 0,1)

(Ex.)

(Ex.)			
Rated voltage Dimension code	DC25V	DC50V	DC100V
0,1	104K	103K	224K
2	G ⁴⁷⁵ K2C	C ¹⁰⁵ K5C	(P ¹⁰⁵ K1C
3,W	(M 476) K2C	& 226 K5C	(A 475) K1C

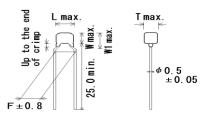
4. Part number list



Oustan			DC		0		Dime	ension (mm)		Dimension	Pa
Customer Part Number	Murata Part Number	T.C.	Rated Volt. (V)	Cap.	Cap. Tol.	L	W	W1	F	т	(LxW) Lead Style	c (p
	RDER71E104K0P1H03B	X7R	25	0.10µF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	5
	RDEC71E224K0P1H03B	X7S	25	0.22µF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	Ę
	RDEC71E474K0P1H03B	X7S	25	0.47µF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ţ
	RDEC71E105K0P1H03B	X7S	25	1.0µF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ę
	RDEC71E225K1P1H03B	X7S	25	2.2µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	ļ
	RDEC71E475K2P1H03B	X7S	25	4.7µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	1
	RDEC71E106K2P1H03B	X7S	25	10µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	4
	RDEC71E226K3P1H03B	X7S	25	22µF	±10%	5.5	5.0	7.5	2.5	4.0	3P1	ļ
	RDER71H221K0P1H03B	X7R	50	220pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H331K0P1H03B	X7R	50	330pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ļ
	RDER71H471K0P1H03B	X7R	50	470pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	4
	RDER71H681K0P1H03B	X7R	50	680pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	4
	RDER71H102K0P1H03B	X7R	50	1000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H152K0P1H03B	X7R	50	1500pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H222K0P1H03B	X7R	50	2200pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H332K0P1H03B	X7R	50	3300pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	4
	RDER71H472K0P1H03B	X7R	50	4700pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H682K0P1H03B	X7R	50	6800pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H103K0P1H03B	X7R	50	10000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H153K0P1H03B	X7R	50	15000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	4
	RDER71H223K0P1H03B	X7R	50	22000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H333K0P1H03B	X7R	50	33000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H473K0P1H03B	X7R	50	47000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H683K0P1H03B	X7R	50	68000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER71H104K0P1H03B	X7R	50	0.10µF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	3
	RDER71H154K1P1H03B	X7R	50	0.15µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	1
	RDER71H224K1P1H03B	X7R	50	0.22µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	;
	RDER71H334K1P1H03B	X7R	50	0.33µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	į
	RDER71H474K1P1H03B	X7R	50	0.47µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	1
	RDER71H684K2P1H03B	X7R	50	0.68µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	ļ
	RDEC71H105K1P1H03B	X7S	50	1.0µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	ļ
	RDER71H105K2P1H03B	X7R	50	1.0µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	ļ
	RDER71H155K2P1H03B	X7R	50	1.5µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	ļ
	RDER71H225K2P1H03B	X7R	50	2.2µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	ļ
	RDER71H335K3P1H03B	X7R	50	3.3µF	±10%	5.5	5.0	7.5	2.5	4.0	3P1	ļ
	RDEC71H475K2P1H03B	X7S	50	4.7µF	±10%	5.5	4.0	6.0	2.5	3.15	2P1	ļ
	RDEC71H106K3P1H03B	X7S	50	10µF	±10%	5.5	5.0	7.5	2.5	4.0	3P1	ļ
	RDER72A221K0P1H03B	X7R	100	220pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ļ
	RDER72A331K0P1H03B	X7R	100	330pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ţ
	RDER72A471K0P1H03B	X7R	100	470pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	

•Outside Cr (Lead Style				• Inside (Lead	e Crimp Style∶K*j)						
E + 0 Up to the end	5		4 v + v + v + v + v + v + v + v + v + v		25.0 min. Wmax.	~	max. ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓	5 0. 05				
	·	ſ	1			1					Unit : mm	1
Customer	Murata Part Number	T.C.	DC Rated	Cap.	Cap.		Dime	ension (mm)		Dimension (LxW)	F
Part Number			Volt. (V)	oup.	Tol.	L	W	W1	F	т	Lead Style	
	RDER72A681K0P1H03B	X7R	100	680pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER72A102K0P1H03B	X7R	100	1000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	;
	RDER72A152K0P1H03B	X7R	100	1500pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ļ
	RDER72A222K0P1H03B	X7R	100	2200pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	ļ
	RDER72A332K0P1H03B	X7R	100	3300pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER72A472K0P1H03B	X7R	100	4700pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER72A682K0P1H03B	X7R	100	6800pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER72A103K0P1H03B	X7R	100	10000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	
	RDER72A153K0P1H03B	X7R	100	15000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	_
	RDER72A223K0P1H03B	X7R	100	22000pF	±10%	5.0	3.5	6.0	2.5	2.5	0P1	1
	RDER72A333K1P1H03B	X7R	100	33000pF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	
	RDER72A473K1P1H03B	X7R	100	47000pF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	
	RDER72A683K1P1H03B	X7R X7R	100	68000pF	±10% ±10%	5.0	3.5	5.0	2.5	3.15	1P1	
	RDER72A104K1P1H03B RDER72A154K2P1H03B	X7R X7R	100 100	0.10µF 0.15µF	±10%	5.0 5.5	3.5 4.0	5.0 6.0	2.5 2.5	3.15 3.15	1P1 2P1	1
	RDER72A224K1P1H03B	X7R	100	0.13µF	±10%	5.0	4.0 3.5	5.0	2.5	3.15	1P1	
	RDER72A334K1P1H03B	X7R	100	0.22µľ 0.33µF	±10%	5.0	3.5	5.0	2.5	3.15	1P1	
	RDER72A474K1P1H03B	X7R	100	0.00µr 0.47µF	±10%	5.0	3.5	5.0				
	RDER72A684K2P1H03B	X7R	100	0.68µF	±10%	5.5	4.0	6.0	2.5	3.15		
	RDER72A105K2P1H03B	X7R	100	1.0µF	±10%	5.5	4.0	6.0	2.5	3.15		
	RDEC72A155K3P1H03B	X7S	100	1.5µF	±10%	5.5	5.0	7.5	2.5	4.0		
	RDEC72A225K3P1H03B	X7S	100	2.2µF	±10%	5.5	5.0	7.5	2.5	4.0	3P1	
	RDEC72A475K3P1H03B	X7S	100	4.7µF	±10%	5.5	5.0	7.5	2.5	4.0	3P1	
	RDER71E104K0K1H03B	X7R	25	0.10µF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	ł
	RDEC71E224K0K1H03B	X7S	25	0.22µF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	ł
	RDEC71E474K0K1H03B	X7S	25	0.47µF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	1
	RDEC71E105K0K1H03B	X7S	25	1.0µF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	
	RDEC71E225K1K1H03B	X7S	25	2.2µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	
	RDEC71E475K2K1H03B	X7S	25	4.7µF	±10%	5.5	4.0	6.0	5.0	3.15		
	RDEC71E106K2K1H03B	X7S	25	10µF	±10%	5.5	4.0	6.0	5.0	3.15		1
	RDEC71E226K3K1H03B	X7S	25	22µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	1
	RDEC71E476MWK1H03B	X7S	25	47µF	±20%	5.5	7.5	10.0	5.0	4.0	WK1	1
	RDER71H221K0K1H03B	X7R	50	220pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	ł
	RDER71H331K0K1H03B RDER71H471K0K1H03B	X7R X7R	50 50	330pF 470pF	±10% ±10%	4.0 4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5 2.5	0K1 0K1	2
	RDER71H471K0K1H03B	X7R X7R	50 50	470pF 680pF	±10% ±10%	4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5	0K1 0K1	;
	RDER71H081K0K1H03B	X7R X7R	50 50	1000pF	±10% ±10%	4.0	3.5 3.5	6.0	5.0 5.0	2.5	0K1 0K1	
						4.0	3.5					-
	RDER71H152K0K1H03B	X7R	50	1500pF	±10%	2 1 1		6.0	5.0	2.5	0K1	1

-	Inside Cri	mp
	(Lead Style	e∶K*)

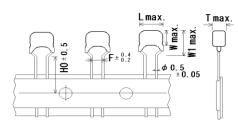


Customer			DC Rated		Cap.		Dime	ension (mm)		Dimension	Pa
Part Number	Murata Part Number	T.C.	Volt. (V)	Cap.	Tol.	L	W	W1	F	Т	(LxW) Lead Style	qi (p
	RDER71H472K0K1H03B	X7R	50	4700pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H682K0K1H03B	X7R	50	6800pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H103K0K1H03B	X7R	50	10000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H153K0K1H03B	X7R	50	15000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H223K0K1H03B	X7R	50	22000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H333K0K1H03B	X7R	50	33000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H473K0K1H03B	X7R	50	47000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H683K0K1H03B	X7R	50	68000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H104K0K1H03B	X7R	50	0.10µF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER71H154K1K1H03B	X7R	50	0.15µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER71H224K1K1H03B	X7R	50	0.22µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER71H334K1K1H03B	X7R	50	0.33µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER71H474K1K1H03B	X7R	50	0.47µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER71H684K2K1H03B	X7R	50	0.68µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	5
	RDEC71H105K1K1H03B	X7S	50	1.0µF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER71H105K2K1H03B	X7R	50	1.0µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	5
	RDER71H155K2K1H03B	X7R	50	1.5µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	5
	RDER71H225K2K1H03B	X7R	50	2.2µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	5
	RDER71H335K3K1H03B	X7R	50	3.3µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	5
	RDEC71H475K2K1H03B	X7S	50	4.7µF	±10%	5.5	4.0	6.0	5.0	3.15	2K1	5
	RDEC71H106K3K1H03B	X7S	50	10µF	±10%	5.5	5.0	7.5	5.0	4.0	3K1	5
	RDEC71H226MWK1H03B	X7S	50	22µF	±20%	5.5	7.5	10.0	5.0	4.0	WK1	5
	RDER72A221K0K1H03B	X7R	100	220pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A331K0K1H03B	X7R	100	330pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A471K0K1H03B	X7R	100	470pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A681K0K1H03B	X7R	100	680pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A102K0K1H03B	X7R	100	1000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A152K0K1H03B	X7R	100	1500pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A222K0K1H03B	X7R	100	2200pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A332K0K1H03B	X7R	100	3300pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A472K0K1H03B	X7R	100	4700pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A682K0K1H03B	X7R	100	6800pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A103K0K1H03B	X7R	100	10000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A153K0K1H03B	X7R	100	15000pF	±10%	4.0	3.5	6.0	5.0	2.5		5
	RDER72A223K0K1H03B	X7R	100	22000pF	±10%	4.0	3.5	6.0	5.0	2.5	0K1	5
	RDER72A333K1K1H03B	X7R	100	33000pF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER72A473K1K1H03B	X7R	100	47000pF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER72A683K1K1H03B	X7R	100	68000pF	±10%	4.5	3.5	5.0	5.0	3.15	1K1	5
	RDER72A104K1K1H03B	X7R	100	0.10µF	±10%	4.5	3.5	5.0	5.0	3.15		5
	RDER72A154K2K1H03B	X7R	100	0.15µF	±10%	5.5	4.0	6.0	5.0	3.15		5

- Inside Cr (Lead Styl P	e∶K*)	05										
			DC				Dime	ension (mm)		Unit : mm	_
Customer Part Number	Murata Part Number	T.C.	Rated Volt.	Cap.	Cap. Tol.	L	W	W1	F	т	Dimension (LxW) Lead Style	qty
			(V)							-		
	RDER72A224K1K1H03B	X7R	100	0.22µF	±10%	4.5	3.5	5.0	5.0	3.15		50
	RDER72A334K1K1H03B	X7R	100	0.33µF	±10%	4.5	3.5	5.0	5.0	3.15		50
	RDER72A474K1K1H03B	X7R	100	0.47µF	±10%	4.5	3.5	5.0	5.0	3.15		50 50
	RDER72A684K2K1H03B RDER72A105K2K1H03B	X7R X7R	100 100	0.68µF 1.0µF	±10% ±10%	5.5 5.5	4.0 4.0	6.0 6.0	5.0 5.0	3.15 3.15		50 50
	RDEC72A155K3K1H03B	X7S	100	1.5µF	±10%	5.5	4.0 5.0	7.5	5.0	4.0		50
	RDEC72A225K3K1H03B	X7S	100	2.2µF	±10%	5.5	5.0	7.5	5.0	4.0		50
	RDEC72A475K3K1H03B	X7S	100	4.7μF	±10%	5.5	5.0	7.5	5.0	4.0		50
	RDEC72A475MWK1H03B	X7S	100	4.7μF	±10%	5.5	7.5	10.0	5.0	4.0		50

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 Outside Crimp Taping (Lead Style:S*)

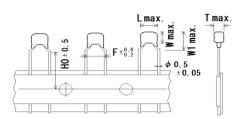


Customer		T 0	DC Rated		Cap.		Di	imensi	on (mn	n)		Dimension	
Part Number	Murata Part Number	T.C.	Volt. (V)	Cap.	Tol.	L	W	W1	F	Т	H/H0	(LxW) Lead Style	qt (po
	RDER71E104K0S1H03A	X7R	25	0.10µF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDEC71E224K0S1H03A	X7S	25	0.22µF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDEC71E474K0S1H03A	X7S	25	0.47µF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDEC71E105K0S1H03A	X7S	25	1.0µF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDEC71E225K1S1H03A	X7S	25	2.2µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDEC71E475K2S1H03A	X7S	25	4.7µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDEC71E106K2S1H03A	X7S	25	10µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDEC71E226K3S1H03A	X7S	25	22µF	±10%	5.5	5.0	7.5	2.5	4.0	16.0	3S1	15
	RDER71H221K0S1H03A	X7R	50	220pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H331K0S1H03A	X7R	50	330pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H471K0S1H03A	X7R	50	470pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H681K0S1H03A	X7R	50	680pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H102K0S1H03A	X7R	50	1000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H152K0S1H03A	X7R	50	1500pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H222K0S1H03A	X7R	50	2200pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H332K0S1H03A	X7R	50	3300pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H472K0S1H03A	X7R	50	4700pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H682K0S1H03A	X7R	50	6800pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H103K0S1H03A	X7R	50	10000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H153K0S1H03A	X7R	50	15000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H223K0S1H03A	X7R	50	22000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H333K0S1H03A	X7R	50	33000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H473K0S1H03A	X7R	50	47000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H683K0S1H03A	X7R	50	68000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H104K0S1H03A	X7R	50	0.10µF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER71H154K1S1H03A	X7R	50	0.15µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDER71H224K1S1H03A	X7R	50	0.22µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDER71H334K1S1H03A	X7R	50	0.33µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDER71H474K1S1H03A	X7R	50	0.47µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDER71H684K2S1H03A	X7R	50	0.68µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDEC71H105K1S1H03A	X7S	50	1.0µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	20
	RDER71H105K2S1H03A	X7R	50	1.0µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDER71H155K2S1H03A	X7R	50	1.5µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDER71H225K2S1H03A	X7R	50	2.2µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDER71H335K3S1H03A	X7R	50	3.3µF	±10%	5.5	5.0	7.5	2.5	4.0	16.0	3S1	15
	RDEC71H475K2S1H03A	X7S	50	4.7µF	±10%	5.5	4.0	6.0	2.5	3.15	16.0	2S1	20
	RDEC71H106K3S1H03A	X7S	50	10µF	±10%	5.5	5.0	7.5	2.5	4.0	16.0	3S1	15
	RDER72A221K0S1H03A	X7R	100	220pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER72A331K0S1H03A	X7R	100	330pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20
	RDER72A471K0S1H03A	X7R	100	470pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	20

PNLIST

•Outside ((Lead Sty	Crimp Taping le:S*)	·Inside Crimp Taping (Lead Style:M*)											
HIDAD		T	X.		HO ± 0.5		E ± 0.6		× xem IX 0.5 ± 0.05	T max.			
Customer Part Number	Murata Part Number	T.C.	DC Rated Volt.	Cap.	Cap. Tol.		D	imensi W1	on (mn F	n) T	н/но	Unit : mm Dimension (LxW) Lead Style	qty.
			(V)						-	-			
	RDER72A681K0S1H03A	X7R	100	680pF	±10%	5.0	3.5	6.0	2.5	2.5		0S1	2000
	RDER72A102K0S1H03A	X7R	100	1000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A152K0S1H03A	X7R	100	1500pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A222K0S1H03A	X7R	100	2200pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A332K0S1H03A	X7R	100	3300pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A472K0S1H03A	X7R	100	4700pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A682K0S1H03A	X7R	100	6800pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A103K0S1H03A	X7R	100	10000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A153K0S1H03A	X7R	100	15000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A223K0S1H03A	X7R	100	22000pF	±10%	5.0	3.5	6.0	2.5	2.5	16.0	0S1	2000
	RDER72A333K1S1H03A	X7R	100	33000pF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	2000
	RDER72A473K1S1H03A	X7R	100	47000pF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	2000
	RDER72A683K1S1H03A	X7R	100	68000pF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	2000
	RDER72A104K1S1H03A	X7R	100	0.10µF	±10%	5.0	3.5	5.0	2.5	3.15		1S1	2000
	RDER72A154K2S1H03A	X7R	100	0.15µF	±10%	5.5	4.0	6.0	2.5	3.15		2S1	2000
	RDER72A224K1S1H03A	X7R	100	0.22µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	2000
	RDER72A334K1S1H03A	X7R	100	0.33µF	±10%	5.0	3.5	5.0	2.5	3.15	16.0	1S1	2000
	RDER72A474K1S1H03A	X7R	100	0.47µF	±10%	5.0	3.5	5.0	2.5	3.15		1S1	2000
	RDER72A684K2S1H03A	X7R	100	0.68µF	±10%	5.5	4.0	6.0	2.5			2S1	2000
	RDER72A105K2S1H03A	X7R	100	1.0µF	±10%	5.5	4.0	6.0	2.5	3.15		2S1	2000
	RDEC72A155K3S1H03A	X7S	100	1.5µF	±10%	5.5	5.0	7.5	2.5	4.0		3S1	1500
	RDEC72A225K3S1H03A	X7S	100	2.2µF	±10%	5.5	5.0	7.5	2.5	4.0		3S1	1500
	RDEC72A475K3S1H03A	X7S	100	4.7µF	±10%	5.5	5.0	7.5	2.5	4.0		3S1	2000
	RDER71E104K0M1H03A	X7R	25	0.10µF	±10%	4.0	3.5	6.0	5.0	2.5		0M1	2000
	RDEC71E224K0M1H03A	X7S	25	0.22µF	±10%	4.0	3.5	6.0	5.0	2.5		0M1	2000
	RDEC71E474K0M1H03A	X7S	25	0.47µF	±10%	4.0	3.5	6.0	5.0	2.5		0M1	2000
	RDEC71E105K0M1H03A	X7S	25	1.0µF	±10%	4.0	3.5	6.0	5.0	2.5		0M1	2000
	RDEC71E225K1M1H03A	X7S	25	2.2µF	±10%	4.5	3.5	5.0	5.0	3.15		1M1	2000
	RDEC71E475K2M1H03A	X7S X7S	25	4.7µF	±10%	5.5	4.0	6.0	5.0	3.15		2M1	2000
	RDEC71E106K2M1H03A RDEC71E226K3M1H03A	X7S X7S	25 25	10µF	±10%	5.5	4.0 5.0	6.0 7.5	5.0 5.0	3.15 4.0		2M1 3M1	2000 1500
	RDEC71E226K3M1H03A RDEC71E476MWM1H03A		25 25	22µF	±10% ±20%	5.5 5.5	5.0 7.5	7.5 10.0	5.0 5.0	4.0		WM1	1500
	RDEC71E476MWM1H03A RDER71H221K0M1H03A	X7S X7R	25 50	47µF	±20% ±10%	5.5 4.0	7.5 3.5	10.0 6.0	5.0 5.0	4.0 2.5		0M1	2000
	RDER71H221K0M1H03A RDER71H331K0M1H03A	X7R X7R	50 50	220pF 330pF	±10% ±10%	4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5 2.5		0M1	2000
	RDER71H331K0M1H03A	X7R X7R	50 50	470pF	±10% ±10%	4.0	3.5 3.5	6.0	5.0 5.0	2.5 2.5		0M1	2000
	RDER71H471K0M1H03A	X7R	50 50	470pF 680pF	±10% ±10%	4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5 2.5		0M1	2000
	RDER71H081K0M1H03A	X7R X7R	50 50	1000pF	±10% ±10%	4.0	3.5 3.5	6.0	5.0 5.0	2.5 2.5		0M1	2000
		X7R X7R	50 50			4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5 2.5		0M1	2000
	RDER71H152K0M1H03A RDER71H222K0M1H03A	X7R X7R	50 50	1500pF 2200pF	±10% ±10%	4.0	3.5 3.5	6.0 6.0	5.0 5.0	2.5 2.5		0M1	2000
	RDER71H222K0M1H03A	X7R X7R	50 50	2200pF 3300pF	±10% ±10%	4.0	3.5 3.5	6.0	5.0 5.0	2.5		0M1	2000
			00	0000001	1070	7.0	0.0	0.0	0.0	2.0	10.0		2000

・Inside Crimp Taping (Lead Style:M*)



Customer			DC Rated		Cap.		D	imensi	on (mn	n)		Dimension	
Part Number	Murata Part Number	T.C.	Volt. (V)	Cap.	Tol.	L	W	W1	F	Т	H/H0	(LxW) Lead Style	qt (po
	RDER71H472K0M1H03A	X7R	50	4700pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H682K0M1H03A	X7R	50	6800pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H103K0M1H03A	X7R	50	10000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H153K0M1H03A	X7R	50	15000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H223K0M1H03A	X7R	50	22000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H333K0M1H03A	X7R	50	33000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H473K0M1H03A	X7R	50	47000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H683K0M1H03A	X7R	50	68000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H104K0M1H03A	X7R	50	0.10µF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER71H154K1M1H03A	X7R	50	0.15µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER71H224K1M1H03A	X7R	50	0.22µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER71H334K1M1H03A	X7R	50	0.33µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER71H474K1M1H03A	X7R	50	0.47µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER71H684K2M1H03A	X7R	50	0.68µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20
	RDEC71H105K1M1H03A	X7S	50	1.0µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER71H105K2M1H03A	X7R	50	1.0µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20
	RDER71H155K2M1H03A	X7R	50	1.5µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20
	RDER71H225K2M1H03A	X7R	50	2.2µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20
	RDER71H335K3M1H03A	X7R	50	3.3µF	±10%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	15
	RDEC71H475K2M1H03A	X7S	50	4.7µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20
	RDEC71H106K3M1H03A	X7S	50	10µF	±10%	5.5	5.0	7.5	5.0	4.0	16.0	3M1	15
	RDEC71H226MWM1H03A	X7S	50	22µF	±20%	5.5	7.5	10.0	5.0	4.0	16.0	WM1	15
	RDER72A221K0M1H03A	X7R	100	220pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A331K0M1H03A	X7R	100	330pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A471K0M1H03A	X7R	100	470pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A681K0M1H03A	X7R	100	680pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A102K0M1H03A	X7R	100	1000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A152K0M1H03A	X7R	100	1500pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A222K0M1H03A	X7R	100	2200pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A332K0M1H03A	X7R	100	3300pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A472K0M1H03A	X7R	100	4700pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A682K0M1H03A	X7R	100	6800pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A103K0M1H03A	X7R	100	10000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A153K0M1H03A	X7R	100	15000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A223K0M1H03A	X7R	100	22000pF	±10%	4.0	3.5	6.0	5.0	2.5	16.0	0M1	20
	RDER72A333K1M1H03A	X7R	100	33000pF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER72A473K1M1H03A	X7R	100	47000pF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER72A683K1M1H03A	X7R	100	68000pF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER72A104K1M1H03A	X7R	100	0.10µF	±10%	4.5	3.5	5.0	5.0	3.15	16.0	1M1	20
	RDER72A154K2M1H03A	X7R	100	0.15µF	±10%	5.5	4.0	6.0	5.0	3.15	16.0	2M1	20

Sno	cification				ice only						
.Spe No.	cification Tes	t Item		fication	Toot M	lethod (Pa	f Standard	IIS C 5101/4	all narte) IECO	0384/all parts\\	
NO. 1				fication	Test Method (Ref. Standard:JIS C 5101(all parts), IEC60384(all parts)) Visual inspection.						
2	Appearance	Marking	No defects or abnorm		-		ing Coliner				
2	Dimension and	IVIAIKING	Within the specified di	mensions and	visual insp	ection, US	ing Caliper.				
2	Dialantaia	Detures	Marking	- 1141	The series						
3	Dielectric	Between						laged when v	•		
	Strength	Terminals						erminations f			
					1 to 5 seco	onds. (Cha	irge/Dischar	ge current ≦	₌ 50mA.)		
					I r	Rated	voltage	Te	st voltage		
						DC25V	-				
							00V	250% of the	e rated voltage	e * 1	
						201	001				
		Terminal To	No defects or abnorm	alities.	The capaci	itor is plac	ed in a cont	ainer with me	etal balls		
		External Resin			of 1mm dia	ameter so	that each te	rminal, short	-circuit,		
					is kept app	roximately	/ 2mm from	the balls, an	d		
								1 to 5 secor			
					-		•	metal balls.			
							surrent ≤ 50				
					(Onarge/Di			,			
						Rat	ted voltage		Test voltage		
						DC2	25V•DC50\	250%	of the rated w	oltogo	
						[DC100V	230%	or the rated w	onage	
,			40.000								
4	Insulation	Between	10,000MΩ or 500MΩ •	•				be measured			
	Resistance	Terminals	(Whichever is smaller))	DC voltage	e not excee	eding the ra	ted voltage a	t normal		
	(I.R.)				temperatur	e and hun	nidity and wi	thin 2 minute	s of		
					charging. (Charge/Di	ischarge cui	rrent ≦ 50m/	A.)		
5	Capacitance		Within the specified to	lerance.	The capaci	itance, D.F	should be	measured a	t 25°C		
					at the frequ	lency and	voltage sho	wn in the tab	le.		
6	Dissipation Fa	ctor (D.F.)	X7R : 0.025 max.		-						
			X7S : 0.125 max.		N	ominal C		requency		tage	
						C≦10µF		1±0.1kHz		:V (r.m.s.)	
						C>10µF	- 1	20±24Hz	AC0.5±0.	1V (r.m.s.)	
7	Capacitance		X7R : within ±15%		The concei	itanaa aha	ngo chould	be measured	l oftor E		
'	-		X7S : within $\pm 22\%$		-		-		aller 5		
	Temperature		∧/3. within ±22%				d temperatu				
	Characteristics	6			-			ge compared			
								ranges show	vn in the		
					table should	d be withir	n the specifi	ed ranges.			
						Г	Cton	Temperat			
						_	Step		()		
						_	1	25±			
						_	2	-55±			
						_	3	25±	2		
							4	125±	:3		
							5	25±	2		
					Pretreatm						
							mont of 450	0/ 1000 4-	000		
								+0/-10°C for			
_	- · ·		-		-			tion for 24±2			
8	Terminal	Tensile	Termination not to be	broken or				body, apply		11441	
	Strength	Strength	loosened		•			e radial direc		ıΤĭ	
					the capacit	or until rea	aching 10N	and then kee	р	Ĕ <u></u>	
					applied the	force for	10±1 secon	ds.			
		Bending	Termination not to be	broken or	Each lead	wire shoul	d be subjec	ted to a force	e of		
		Strength	loosened		2.5N and then be bent 90° at the point of egress in						
				one direction. Each wire is then returned to the							
					original position and bent 90° in the opposite						
					0 1			per 2 to 3 se	conds		
9	Vibration	Appearance	No defects or abnorm	alities				ed to a simple			
5	Resistance				-						
	RESISTANCE	Capacitance	Within the specified to				-	mplitude of			
		D.F.	X7R : 0.025 max.					mly betwee	n the		
			X7S : 0.125 max.				10Hz and 5				
					The freque	ncy range	, from 10Hz	to 55Hz and	return		
					to 10Hz, sh	hall be trav	versed in ap	proximately	1 minute.		
					This motion	n shall be	applied for a	a period of 2	hours in		
								•	l of 6 hours).		
'rooı	n condition" To	mperature 15 t	o 35°C, Relative humid	ity : 45 to 75% Atmo							
		•			oprioro pressu		i ooki a				
Be	elow parts are	••									
	*1 Rated	voltage×200%									
	* 2 I.R. : 50) MΩ·μFmin.									
	Char	Rated Voltag	je Capacitance	Dimensions							
	Char.										
F	Cnar. C7	2A	475	3							

Reference only

).	Tes	t Item	Specification	Test Method (Ref. Standard:JIS C 5101(all parts), IEC60384(all parts)							
0	Solderability		Solder is deposited on unintermittingly	The terminal of capacitor is dipped into a solution of rosin ethanol (25% rosin in weight proportion).							
			immersed portion in axial direction								
			covering 3/4 or more in circumferential	Immerse in solder solution for 2±0.5 seconds.							
			direction of lead wires.	In both cases the depth of dipping is up to about 1.5 to 2mm							
				from the terminal body.							
				Temp. of solder : 245±5°C (Sn-3.0Ag-0.5Cu)							
1-1	Resistance	Appearance	No defects or abnormalities.	The lead wires should be immersed in the melted solder 1.5 to 2.0mm							
	to Soldering	Capacitance	X7R : Within ±7.5%	from the root of terminal at 260±5°C for 10±1 seconds.							
	Heat	Change	X7S : Within ±10%								
	(Non-	Dielectric	No defects.	Pretreatment							
	Preheat)	Strength		Capacitor should be stored at 150+0/-10°C for one hour, then place at							
		(Between		*room condition for 24±2 hours before initial measurement.							
		terminals)		Post-treatment							
		,		Capacitor should be stored for 24±2 hours at *room condition.							
11-2	Resistance	Appearance	No defects or abnormalities.	First the capacitor should be stored at 120+0/-5°C for 60+0/-5 seconds.							
	to Soldering	Capacitance	X7R : Within ±7.5%	Then, the lead wires should be immersed in the melted solder							
	Heat	Change	X7S : Within ±10%	 1.5 to 2.0mm from the root of terminal at 260±5°C for 7.5+0/-1 seconds. Pretreatment Capacitor should be stored at 150+0/-10°C for one hour, then place at 							
	(On-	Dielectric	No defects.								
	Preheat)	Strength									
	,	(Between									
		terminals)		*room condition for 24±2 hours before initial measurement.							
		,		Post-treatment							
				Capacitor should be stored for 24±2 hours at *room condition.							
1-3	Resistance	e Appearance No defects or abnormalities.		Test condition							
	to Soldering	Capacitance	X7R : Within ±7.5%	Temperature of iron-tip : 350±10°C							
	Heat	Change	X7S : Within ±10%	Soldering time : 3.5±0.5 seconds							
	(soldering	Dielectric	No defects.	Soldering position Straight Lead : 1.5 to 2.0mm from the root of terminal.							
	iron method)	Strength									
	,	(Between		Crimp Lead : 1.5 to 2.0mm from the end of bend.							
		terminals)									
		(orrelation)		Pretreatment							
				Capacitor should be stored at 150+0/-10°C for one hour, then place at							
				*room condition for 24+2 hours before initial measurement.							
				Post-treatment							
				Capacitor should be stored for 24±2 hours at *room condition.							
12	Temperature	Appearance	No defects or abnormalities.	Repeat 5 cycles according to the 4 heat							
	Cycle	Capacitance	X7R, X7S : Within±12.5%	treatments listed in the following table.							
	- ,	Change	,	Set at *room condition for 24±2 hours, then measure.							
		D.F.	X7R : 0.05 max.								
			X7S : 0.2 max.	Step 1 2 3 4							
		I.R.	1,000MΩ or 50MΩ•μF min.	Temp. Min. Room Max. Room							
			(Whichever is smaller)	(°C) Operating Temp Operating Temp							
		Dielectric	No defects or abnormalities.	Temp. ±3							
		Strength		Time 30±3 3 max. 30±3 3 max.							
		(Between		(min.) 00_0 0 mar 00_0 0 mar							
		Terminals)		Pretreatment							
		· ·····,		Perform a heat treatment at 150+0/-10°C for one							
				hour and then set at *room condition for 24 ± 2 hours.							
13	Humidity	Appearance	No defects or abnormalities.	Set the capacitor at $40\pm2^{\circ}$ C and relative							
	(Steady	Capacitance	X7R, X7S : Within ±15%	humidity 90 to 95% for 500+24/-0 hours.							
	(State)	Change	,	Remove and set for 24 ± 2 hours at *room condition, then measure.							
	5	D.F.	X7R : 0.05 max.								
			X7S : 0.2 max.	Pretreatment							
		I.R.	1,000MΩ or 50MΩ•μF min.								
	I .		1,00010122 01 0010122 µr 111111.	Perform a heat treatment at 150+0/-10°C for one							
			(Whichever is smaller)	hour and then set at *room condition for 24±2 hours.							

Reference only

lo.	Tes	t Item	Specification	Test Method (Ref. Standard: JIS C 5101 (all parts), IEC60384 (all parts))					
14	Humidity	Appearance	No defects or abnormalities.	Apply the rated voltage at 40±2°C and relative					
	Load	Capacitance	X7R, X7S : Within±15%	humidity of 90 to 95% for 500+24/-0 hours.					
		Change		Remove and set for 24±2 hours at *room condition, then measure.					
		D.F.	X7R : 0.05 max.	(Charge/Discharge current \leq 50mA.)					
			X7S : 0.2 max.						
		I.R.	500MΩ or 25MΩ•μF min. * 3	Pretreatment					
			(Whichever is smaller)	Perform a heat treatment at 150+0/-10°C for one					
				hour and then set at *room condition for 24±2 hours.					
15	High	Appearance	No defects or abnormalities.	Apply 150% of the rated voltage at the maximum					
	Temperature	Capacitance	X7R, X7S : Within±15%	operating temperature ±3°C for 1000+48/-0 hours.					
	Load	Change		Remove and set for 24±2 hours at *room condition, then measure.					
		D.F.	X7R : 0.05 max.	(Charge/Discharge current \leq 50mA.)					
			X7S : 0.2 max.						
		I.R.	1,000MΩ or 50 MΩ • μF min. * 4	Pretreatment					
			(Whichever is smaller)	Apply test voltage for one hour at test temperature.					
				Remove and set at *room condition for 24±2 hours.					
16	Solvent	Appearance	No defects or abnormalities.	The capacitor should be fully immersed, unagitated,					
	Resistance	Marking	Legible	in reagent at 20 to 25°C for 30±5 seconds and then					
				remove gently. Marking on the surface of the					
				capacitor shall immediately be visually examined.					
				Reagent : Isopropyl alcohol					

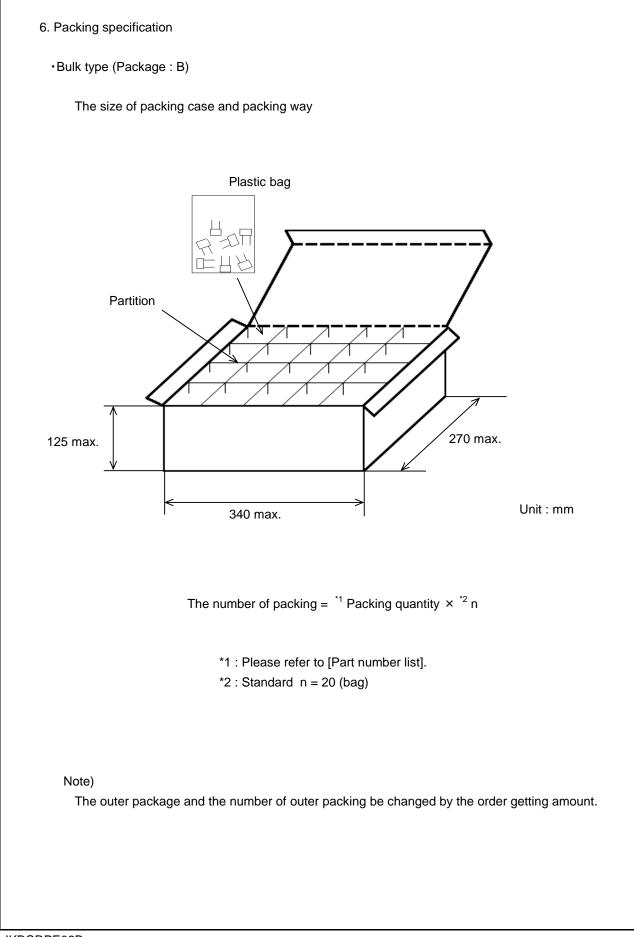
"room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmosphere pressure : 86 to 106kPa

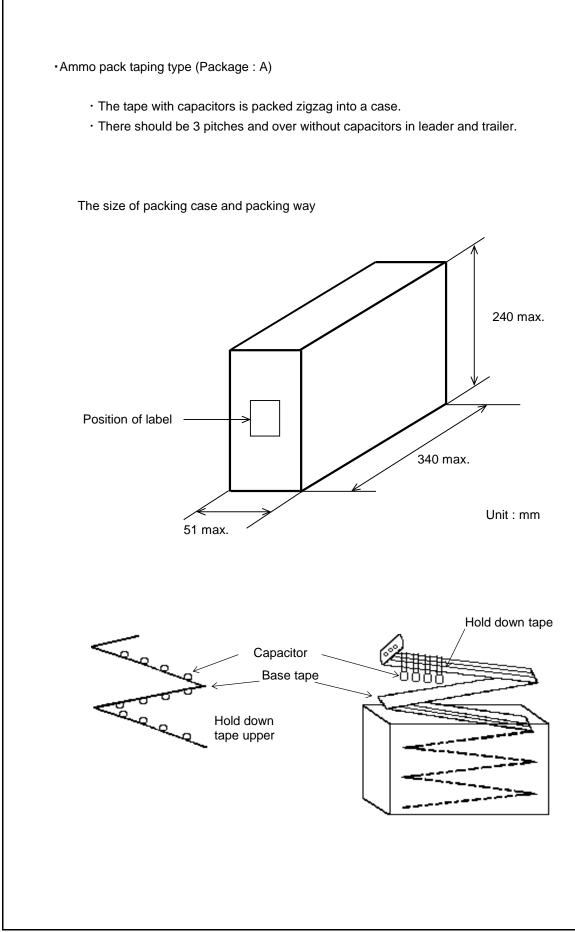
Below parts are applicable in

* 3 I.R. : 12.5 MΩ • μF min.

*4 I.R.: 25 MΩ • μF min.

Char.	Rated Voltage	Capacitance	Dimensions
C7	2A	475	3



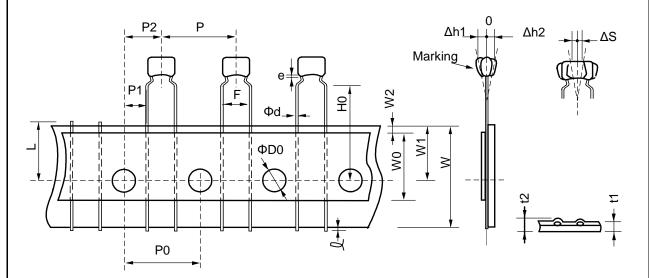


7. Taping specification

7-1. Dimension of capacitors on tape

Inside crimp taping type < Lead Style : M1 >

Pitch of component 12.7mm / Lead spacing 5.0mm

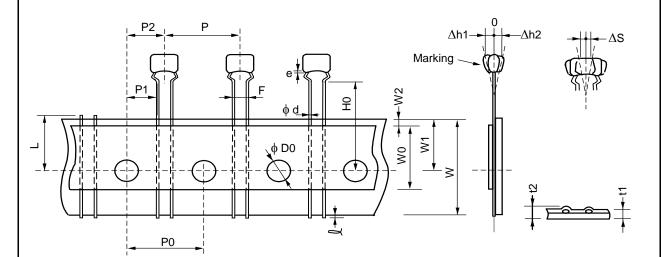


Unit : mm

Item	Code	Dimensions	Remarks
Pitch of component	P	12.7+/-1.0	I Contains
Pitch of sprocket hole	P0	12.7+/-0.2	
Lead spacing	F	5.0+0.6/-0.2	
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction
Length from hole center to lead	P1	3.85+/-0.7	
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bence
Carrier tape width	W	18.0+/-0.5	
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction
Lead distance between reference and bottom plane	H0	16.0+/-0.5	
Protrusion length	l	0.5 max.	
Diameter of sprocket hole	ΦD0	4.0+/-0.1	
Lead diameter	Φd	0.5+/-0.05	
Total tape thickness	t1	0.6+/-0.3	They include hold down tape
Total thickness of tape and lead wire	t2	1.5 max.	thickness
Deviation correct tone	∆h1	2.0 max. (D	imension code : W)
Deviation across tape	∆h2	1.0 max. (e:	xcept as above)
Portion to cut in case of defect	L	11.0+0/-1.0	
Hold down tape width	W0	9.5 min.	
Hold down tape position	W2	1.5+/-1.5	
Coating extension on lead	е	Up to the end of	crimp

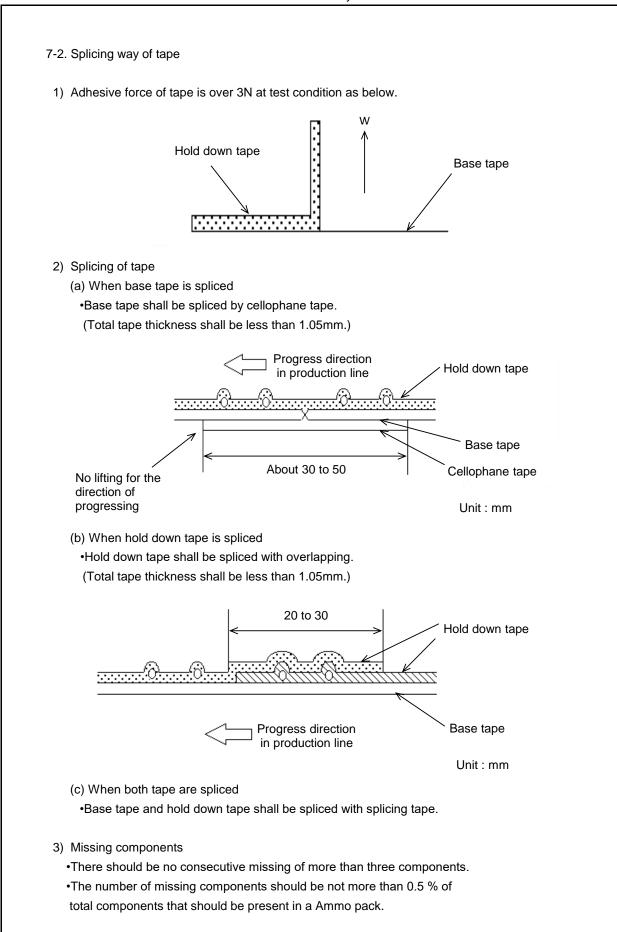
ETP1M101A

Outside crimp taping type < Lead Style : S1 > Pitch of component 12.7mm / Lead spacing 2.5mm



Unit : mm

Item	Code	Dimensions	Remarks
Pitch of component	Р	12.7+/-1.0	
Pitch of sprocket hole	P0	12.7+/-0.2	
Lead spacing	F	2.5+0.4/-0.2	
Length from hole center to component center	P2	6.35+/-1.3	Deviation of progress direction
Length from hole center to lead	P1	5.1+/-0.7	1
Deviation along tape, left or right defect	ΔS	0+/-2.0	They include deviation by lead bence
Carrier tape width	W	18.0+/-0.5	
Position of sprocket hole	W1	9.0+0/-0.5	Deviation of tape width direction
Lead distance between reference and bottom plane	HO	16.0+/-0.5	
Protrusion length	l	0.5 max.	
Diameter of sprocket hole	ΦD0	4.0+/-0.1	
Lead diameter	Φd	0.5+/-0.05	
Total tape thickness	t1	0.6+/-0.3	They include hold down tape
Total thickness of tape and lead wire	t2	1.5 max.	thickness
Deviction corose tone	∆h1	1.0 max.	
Deviation across tape	∆h2	1.0 max.	
Portion to cut in case of defect	L	11.0+0/-1.0	
Hold down tape width	W0	9.5 min.	
Hold down tape position	W2	1.5+/-1.5	
Coating extension on lead	е	Up to the end of	crimp

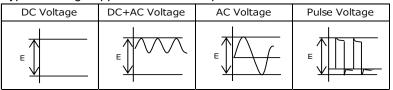


1. OPERATING VOLTAGE

Do not apply a voltage to the capacitor that exceeds the rated voltage as called out in the specifications.

- 1-1. Applied voltage between the terminals of a capacitor shall be less than or equal to the rated voltage.
- (1) When AC voltage is superimposed on DC voltage, the zero-to-peak voltage shall not exceed the rated DC voltage. When AC voltage or pulse voltage is applied, the peak-to-peak voltage shall not exceed the rated DC voltage.
- (2) Abnormal voltages (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated DC voltage.

Typical Voltage Applied to the DC Capacitor



(E: Maximum possible applied voltage.)

1-2. Influence of over voltage

Over voltage that is applied to the capacitor may result in an electrical short circuit caused by the breakdown of the internal dielectric layers. The time duration until breakdown depends on the applied voltage and the ambient temperature.

Use a safety standard certified capacitor in a power supply input circuit (AC filter), as it is also necessary to consider the withstand voltage and impulse withstand voltage defined for each device.

2. OPERATING TEMPERATURE AND SELF-GENERATED HEAT

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself.

When the capacitor is used in a high-frequency current, pulse current or the like, it may have the selfgenerated heat due to dielectric-loss.

In case of Class 2 capacitors (Temp.Char. : X7R,X7S,X8L, etc.), applied voltage should be the load such as self-generated heat is within 20 °C on the condition of atmosphere temperature 25 °C.

Since the self-heating is low in the Class 1 capacitors (Temp.Char.: C0G,U2J,X8G, etc.), the allowable power becomes extremely high compared to the Class 2 capacitors.

However, when a load with self-heating of 20°C is applied at the rated voltage, the allowable power may be exceeded. Please confirm that there is no rising trend of the capacitor's surface temperature and that the surface temperature of the capacitor does not exceed the maximum operating temperature.

Excessive generation of heat may cause deterioration of the characteristics and reliability of the capacitor.

When measuring the self-heating temperature, be aware that accurate measurement may not be possible due to the following effects.

- The heat generated by other parts
- Air flow such as convection and cooling fans
- Temperature sensor used for measuring surface temperature of capacitor In the case using a thermocouple, it is recommended that use a K thermocouple of Φ0.1mm with less heat capacity.

3. FAIL-SAFE

Capacitors that are cracked by dropping or bending of the board may cause deterioration of the insulation resistance, and result in a short.

If the circuit being used may cause an electrical shock, smoke or fire when a capacitor is shorted, be sure to install fail-safe functions, such as a fuse, to prevent secondary accidents.

4. OPERATING AND STORAGE ENVIRONMENT

The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. And avoid exposure to moisture. Before cleaning, bonding, or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 °C and 20 to 70%. Use capacitors within 6 months. Use capacitors within 6 months after delivered. Check the solderability after 6 months or more. Due to moisture condensation caused by rapid humidity changes, or the photochemical change caused by direct sunlight on the terminal electrodes, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or in high humidity conditions.

5. VIBRATION AND IMPACT

Do not expose a capacitor or its leads to excessive shock or vibration during use.

5-1. Mechanical shock due to being dropped may cause damage or a crack in the dielectric material of the capacitor.

Do not use a dropped capacitor because the quality and reliability may be deteriorated.

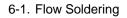
5-2. Excessive shock or vibration may cause to fatigue destruction of lead wires mounted on the circuit board. If necessary, take measures to hold a capacitor on the circuit boards by adhesive, molding resin or coating and other.

Please confirm there is no influence of holding measures on the product with an intended equipment.

6. SOLDERING

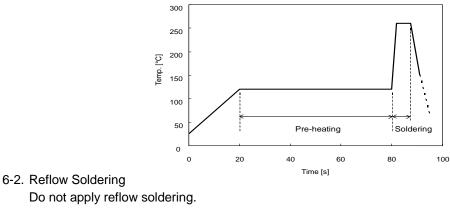
When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

Please verify that the soldering process does not affect the quality of capacitors.



Soldering temperature Soldering time Preheating temperature Preheating time : 260 °C max. : 7.5 s max. : 120 °C max. : 60 s max.

[Standard Condition for Flow Soldering]



7. BONDING AND RESIN MOLDING, RESIN COAT

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of capacitor by testing the performance of a bonded or molded product in the intended equipment. In case of the amount of applications, dryness / hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor is damaged by the organic solvents and it may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin may cause a outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

8. TREATMENT AFTER BONDING AND RESIN MOLDING, RESIN COAT

When the outer coating is hot (over 100 °C) after soldering, it becomes soft and fragile. So please be careful not to give it mechanical stress.

Failure to follow the above cautions may result, worst case, in a short circuit and cause fuming or partial dispersion when the product is used.

9. LIMITATION OF APPLICATIONS

The products listed in the specification(hereinafter the product(s) is called as the "Product(s)") are designed and manufactured for applications specified in the specification. (hereinafter called as the "Specific Application")

We shall not warrant anything in connection with the Products including fitness, performance, adequateness, safety, or quality, in the case of applications listed in from (1) to (11) written at the end of this precautions, which may generally require high performance, function, quality, management of production or safety.

Therefore, the Product shall be applied in compliance with the specific application.

WE DISCLAIM ANY LOSS AND DAMAGES ARISING FROM OR IN CONNECTION WITH THE PRODUCTS INCLUDING BUT NOT LIMITED TO THE CASE SUCH LOSS AND DAMAGES CAUSED BY THE UNEXPECTED ACCIDENT, IN EVENT THAT (i) THE PRODUCT IS APPLIED FOR THE PURPOSE WHICH IS NOT SPECIFIED AS THE SPECIFIC APPLICATION FOR THE PRODUCT, AND/OR (ii) THE PRODUCT IS APPLIED FOR ANY FOLLOWING APPLICATION PURPOSES FROM (1) TO (11) (EXCEPT THAT SUCH APPLICATION PURPOSE IS UNAMBIGUOUSLY SPECIFIED AS SPECIFIC APPLICATION FOR THE PRODUCT IN THE SPECIFICATION.*)

- 1. Aircraft equipment
- 2. Aerospace equipment
- 3. Undersea equipment
- 4. Power plant control equipment
- 5. Medical equipment
- 6. Transportation equipment
- 7. Traffic control equipment
- 8. Disaster prevention/security equipment
- 9. Industrial data-processing equipment
- 10. Combustion/explosion control equipment
- 11. Equipment with complexity and/or required reliability equivalent to the applications listed in the above.

For exploring information of the Products which will be compatible with the particular purpose other than those specified in the specification, please contact our sales offices, distribution agents, or trading companies with which you make a deal, or via our web contact form.

Contact form: https://www.murata.com/contactform

*We may design and manufacture particular Products for applications listed in (1) to (11). Provided that, in such case we shall unambiguously specify such Specific Application in the specification without any exception.

Therefore, any other documents and/or performances, whether exist or non-exist, shall not be deemed as the evidence to imply that we accept the applications listed in (1) to (11).

NOTICE

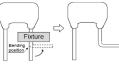
1. CLEANING

- 1-1. Please evaluate the capacitor using actual cleaning equipment and conditions to confirm the quality, and select the solvent for cleaning.
- 1-2. Unsuitable cleaning may leave residual flux or other foreign substances, causing deterioration of electrical characteristics and the reliability of the capacitors.
- 1-3. To perform ultrasonic cleaning, observe the following conditions. Rinse bath capacity : Output of 20 watts per liter or less. Rinsing time : 5 min maximum. Do not vibrate the PCB/PWB directly. Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

2. SOLDERING AND MOUNTING

- 2-1. Insert the lead wire into the PCB with a distance appropriate to the lead space. If the lead wires are inserted into different spacing holes, cracks may occur in the outer resin or the internal element.
- 2-2. When bending the lead wire, excessive force applied to the capacitor body may cause cracks in the outer resin or the internal element. Hold the lead wire closer to the capacitor body than the lead wire bending position with the fixture, then bend it.

(See the right figure)



- 2-3. When cutting and clinching the lead wire, do not apply excessive force to the capacitor body.
- 2-4. When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.

3. CAPACITANCE CHANGE OF CAPACITORS

Class 2 capacitors (Temp.Char. : X7R,X7S,X8L etc.)

Class 2 capacitors an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor leaves for a long time. Moreover, capacitance might change greatly depending on a surrounding temperature or an applied voltage. So, it is not likely to be able to use for the time constant circuit.

Please contact us if you need a detail information.

4. CHARACTERISTICS EVALUATION IN THE ACTUAL SYSTEM

- 4-1. Evaluate the capacitor in the actual system, to confirm that there is no problem with the performance and specification values in a finished product before using.
- 4-2. Since a voltage dependency and temperature dependency exists in the capacitance of Class 2 ceramic capacitors, the capacitance may change depending on the operating conditions in the actual system. Therefore, be sure to evaluate the various characteristics, such as the leakage current and noise absorptivity, which will affect the capacitance value of the capacitor.
- 4-3. In addition, voltages exceeding the predetermined surge may be applied to the capacitor by the inductance in the actual system.

Evaluate the surge resistance in the actual system as required.

4-4. When using Class 2 ceramic capacitors in AC or pulse circuits, the capacitor itself vibrates at specific frequencies and noise may be generated. Moreover, when the mechanical vibration or shock is added to capacitor, noise may occur.

- 1. Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- 2. You are requested not to use our product deviating from this product specification.